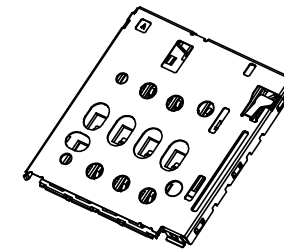
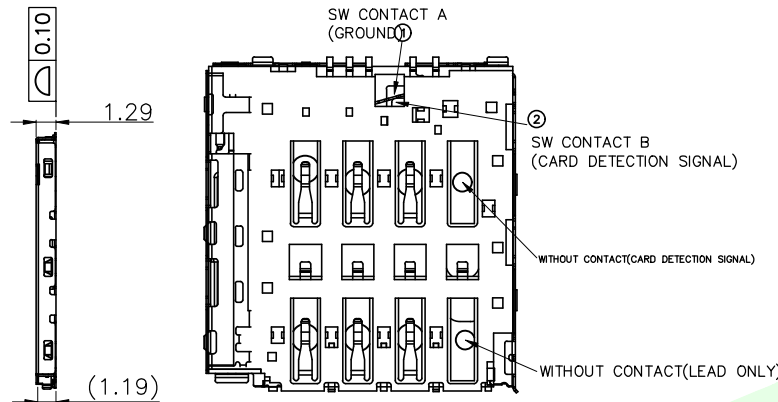
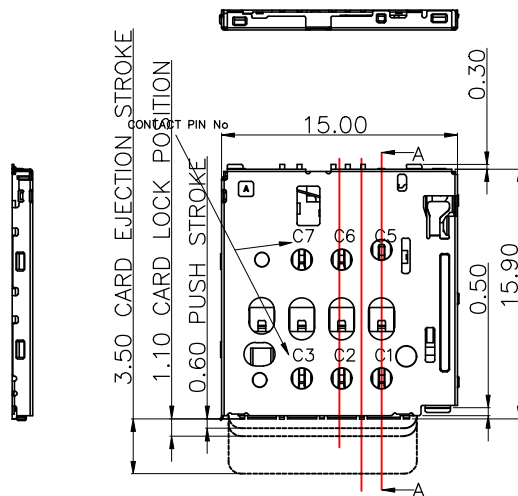


RoHS Compliant



NOTES:

3D REFERENCE MODEL

MATERIAL:

Housing: High Temperature Thermoplastic, UL 94V-0.

Contact: Copper Alloy

Shell: SUS

PLATING:

Contact: Contact Area: Au 1u", Solder area: Gold Flash;

Shell: Plated 30u" Min all over

Solder area: Gold

Electrical: Flash

Current Rating :0.5mA max.

Voltage Rating :50V DC MAX

Ambient Temperature Range : -20°C~+85°C

Storage Temperature Range : -40°C~+70°C

Ambient Humidity Range :95% R.H. Max.

Contact Resistance:100mΩ max.

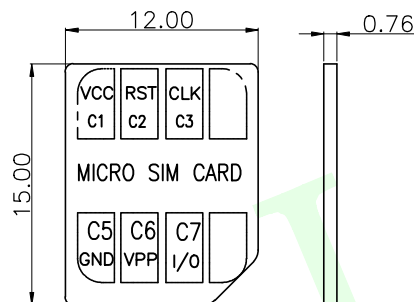
Insulation Resistance:1000MΩ min./250V DC

Dielectric Withstanding Voltage:500V AC

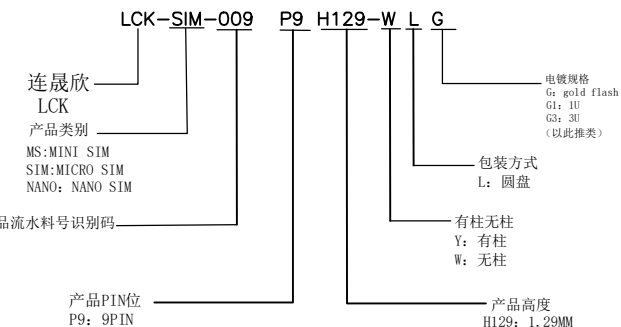
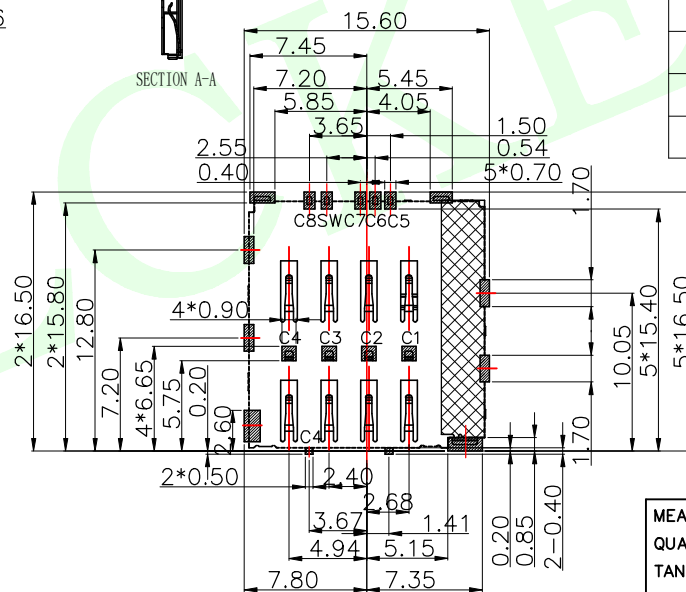
Mating Cycles:3,000 Insertions

Temperature: 260°C ±5°

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



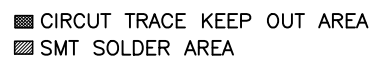
SECTION A-A



CARD INSERTION STATE	CARD DETECT SW
CARD UN-INSERTION	CLOSE
CARD INSERTION	OPEN

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05



MEASURE POINT:

QUADRANT POINT (QP)

TANGENCY POINT (TP)

INTERSECTION POINT (IP)

UNLESS OTHERWISE SPECIFIED, TOLERANCE:

X.	± 0.25
X.x	± 0.20
X.xx	± 0.15
ANGULAR	$\pm 3^\circ$

联晟欣连接器 (深圳) 有限公司
Lianshengxin Connector (Shenzhen) Co., Ltd

DESIGN	Andy	DATE	2014.12.24	TITLE:	MICRO SIM CARD PUSH PUSH 9PIN
CHECKED		DATE			1.29H卡座
APPROVED		DATE			
PART NO:	LCK-SIM-009P9H129-WLG	REV:	04	SCALE:	1:1
DRAWING NO:	1020221030	SIZE:	A4	SHEET:	1/1